Renesas Electronics America Inc - R5F2L3A8CDFA#U0 Datasheet

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	R8C
Core Size	16-Bit
Speed	20MHz
Connectivity	I²C, LINbus, SIO, SSU, UART/USART
Peripherals	LCD, POR, PWM, Voltage Detect, WDT
Number of I/O	88
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 20x10b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-BQFP
Supplier Device Package	100-QFP (14x20)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f2l3a8cdfa-u0

Table 1.2 Programmable I/O Ports Provided for Each Group

Programmable I/O Port	R8C/L35C Group Total: 41 I/O pins								R8C/L36C Group Total: 52 I/O pins								R8C/L38C Group Total: 68 I/O pins								R8C/L3AC Group Total: 88 I/O pins							
	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0
P0	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
P1	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
P2	✓	✓	✓	✓	–	–	–	–	✓	✓	✓	✓	–	–	–	–	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
P3	–	–	–	–	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
P4	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
P5	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	✓	✓	✓	✓
P6	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
P7	✓	✓	✓	✓	–	–	–	–	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
P10	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	✓	✓	✓	✓	✓	✓	✓	✓
P11	–	–	–	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
P12	–	–	–	–	✓	✓	✓	✓	–	–	–	–	✓	✓	✓	✓	–	–	–	–	✓	✓	✓	✓	–	–	–	–	✓	✓	✓	✓
P13	–	–	–	–	✓	✓	✓	✓	–	–	–	–	✓	✓	✓	✓	–	–	–	–	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓

Notes:
1. The symbol "✓" indicates a programmable I/O port.
2. The symbol "–" indicates the settings should be made as follows:
   - Set 1 to the corresponding bits in the PDi (i = 1 to 3, 5 to 7, and 10 to 13) register.
   - Set 0 to the corresponding bits in the Pi (i = 1 to 3, 5 to 7, and 10 to 13) register.
   - Set 0 to the corresponding bits in the P10DRR or P11DRR register.

Table 1.3 LCD Display Function Pins Provided for Each Group

Shared I/O Port	L35C Group Common output: Max. 4 Segment output: Max. 24								L36C Group Common output: Max. 8 Segment output: Max. 32								L38C Group Common output: Max. 8 Segment output: Max. 48								L3AC Group Common output: Max. 8 Segment output: Max. 56							
P0	SEG 7	SEG 6	SEG 5	SEG 4	SEG 3	SEG 2	SEG 1	SEG 0	SEG 7	SEG 6	SEG 5	SEG 4	SEG 3	SEG 2	SEG 1	SEG 0	SEG 7	SEG 6	SEG 5	SEG 4	SEG 3	SEG 2	SEG 1	SEG 0	SEG 7	SEG 6	SEG 5	SEG 4	SEG 3	SEG 2	SEG 1	SEG 0
P1	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	SEG 11	SEG 10	SEG 9	SEG 8	SEG 15	SEG 14	SEG 13	SEG 12	SEG 11	SEG 10	SEG 9	SEG 8
P2	SEG 23	SEG 22	SEG 21	SEG 20	–	–	–	–	SEG 23	SEG 22	SEG 21	SEG 20	–	–	–	–	SEG 23	SEG 22	SEG 21	SEG 20	SEG 19	SEG 18	SEG 17	SEG 16	SEG 23	SEG 22	SEG 21	SEG 20	SEG 19	SEG 18	SEG 17	SEG 16
P3	–	–	–	–	SEG 27	SEG 26	SEG 25	SEG 24	SEG 31	SEG 30	SEG 29	SEG 28	SEG 27	SEG 26	SEG 25	SEG 24	SEG 31	SEG 30	SEG 29	SEG 28	SEG 27	SEG 26	SEG 25	SEG 24	SEG 31	SEG 30	SEG 29	SEG 28	SEG 27	SEG 26	SEG 25	SEG 24
P4	SEG 39	SEG 38	SEG 37	SEG 36	SEG 35	SEG 34	SEG 33	SEG 32	SEG 39	SEG 38	SEG 37	SEG 36	SEG 35	SEG 34	SEG 33	SEG 32	SEG 39	SEG 38	SEG 37	SEG 36	SEG 35	SEG 34	SEG 33	SEG 32	SEG 39	SEG 38	SEG 37	SEG 36	SEG 35	SEG 34	SEG 33	SEG 32
P5	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	SEG 43	SEG 42	SEG 41	SEG 40
P6	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	SEG 51	SEG 50	SEG 49	SEG 48	SEG 47	SEG 46	SEG 45	SEG 44	SEG 51	SEG 50	SEG 49	SEG 48	SEG 47	SEG 46	SEG 45	SEG 44
P7	COM 0	COM 1	COM 2	COM 3	–	–	–	–	COM 0	COM 1	COM 2	COM 3	SEG 55	SEG 54	SEG 53	SEG 52	COM 0	COM 1	COM 2	COM 3	SEG 55	SEG 54	SEG 53	SEG 52	COM 0	COM 1	COM 2	COM 3	SEG 55	SEG 54	SEG 53	SEG 52
P12	–	–	–	–	CL2	CL1	–	–	–	–	–	–	CL2	CL1	–	–	–	–	–	–	CL2	CL1	–	–	–	–	–	–	CL2	CL1	–	–
–	VL1								VL1								VL1								VL1							
–	VL2								VL2								VL2								VL2							
–	–								VL3								VL3								VL3							
–	VL4								VL4								VL4								VL4							

Notes:
1. The symbol "–" indicates there is no LCD display function. Set the corresponding bits in registers LSE1 to LSE3, LSE5 to LSE7 to 0 for these pins.
2. SEG52 to SEG55 can be used as COM7 to COM4.
   The R8C/L35C Group does not have pins SEG52 to SEG55, so 1/8 duty cannot be selected.
3. The R8C/L35C Group does not have the VL3 pin, so 1/4 bias cannot be selected. When the internal voltage multiplier is used, 1/2 bias cannot also be selected.

1.1.3 Specifications

Tables 1.4 to 1.6 list the Specifications.

Table 1.4 Specifications (1)

Item	Function		Specification
CPU	Central processing unit		R8C CPU core • Number of fundamental instructions: 89 • Minimum instruction execution time: 50 ns (f(XIN) = 20 MHz, VCC = 2.7 to 5.5 V) 200 ns (f(XIN) = 5 MHz, VCC = 1.8 to 5.5 V) • Multiplier: 16 bits × 16 bits → 32 bits • Multiply-accumulate instruction: 16 bits × 16 bits + 32 bits → 32 bits • Operating mode: Single-chip mode (address space: 1 Mbyte)
Memory	ROM/RAM Data flash		Refer to **Tables 1.7 to 1.10 Product Lists**.
Power Supply Voltage Detection	Voltage detection circuit		• Power-on reset • Voltage detection 3 (detection level of voltage detection 0 and voltage detection 1 selectable)
I/O Ports	Programmable I/O ports	R8C/L35C Group	• CMOS I/O ports: 41, selectable pull-up resistor • High current drive ports: 5
		R8C/L36C Group	• CMOS I/O ports: 52, selectable pull-up resistor • High current drive ports: 8
		R8C/L38C Group	• CMOS I/O ports: 68, selectable pull-up resistor • High current drive ports: 8
		R8C/L3AC Group	• CMOS I/O ports: 88, selectable pull-up resistor • High current drive ports: 16
Clock	Clock generation circuits		4 circuits: XIN clock oscillation circuit XCIN clock oscillation circuit (32 kHz) High-speed on-chip oscillator (with frequency adjustment function) Low-speed on-chip oscillator • Oscillation stop detection: XIN clock oscillation stop detection function • Frequency divider circuit: Division ratio selectable from 1, 2, 4, 8, and 16 • Low-power-consumption modes: Standard operating mode (high-speed clock, low-speed clock, high-speed on-chip oscillator, low-speed on-chip oscillator), wait mode, stop mode, power-off mode
			Real-time clock (timer RE)
Interrupts		R8C/L35C Group	• Number of interrupt vectors: 69 • External Interrupt: 9 ($\overline{\text{INT}}$ × 5, key input × 4) • Priority levels: 7 levels
		R8C/L36C Group	• Number of interrupt vectors: 69 • External Interrupt: 12 ($\overline{\text{INT}}$ × 8, key input × 4) • Priority levels: 7 levels
		R8C/L38C Group	• Number of interrupt vectors: 69 • External Interrupt: 16 ($\overline{\text{INT}}$ × 8, key input × 8) • Priority levels: 7 levels
		R8C/L3AC Group	• Number of interrupt vectors: 69 • External Interrupt: 16 ($\overline{\text{INT}}$ × 8, key input × 8) • Priority levels: 7 levels
Watchdog Timer			• 14 bits × 1 (with prescaler) • Selectable reset start function • Selectable low-speed on-chip oscillator for watchdog timer
DTC (Data Transfer Controller)			• 1 channel • Activation sources: 38 • Transfer modes: 2 (normal mode, repeat mode)

Table 1.6 Specifications (3)

Item	Specification
Flash Memory	• Programming and erasure voltage: VCC = 2.7 to 5.5 V • Programming and erasure endurance: 10,000 times (data flash) 1,000 times (program ROM) • Program security: ROM code protect, ID code check • On-chip debug function • On-board flash rewrite function • Background operation (BGO) function
Operating Frequency/ Supply Voltage	f(XIN) = 20 MHz (VCC = 2.7 to 5.5 V) f(XIN) = 5 MHz (VCC = 1.8 to 5.5 V)
Current Consumption	Typ. 7 mA (VCC = 5.0 V, f(XIN) = 20 MHz) Typ. 3.6 mA (VCC = 3.0 V, f(XIN) = 10 MHz) Typ. 3.5 μA (VCC = 3.0 V, wait mode (f(XCIN) = 32 kHz)) Typ. 2 μA (VCC = 3.0 V, stop mode) Typ. 0.02 μA (VCC = 3.0 V, power-off mode)
Operating Ambient Temperature	-20 to 85°C (N version) -40 to 85°C (D version) (1)

Note:
1. Specify the D version if D version functions are to be used.

Table 1.9 Product List for R8C/L38C Group **Current of Apr 2011**

Part No.	Internal ROM Capacity		Internal RAM Capacity	Package Type	Remarks
	Program ROM	Data Flash			
R5F2L387CNFP	48 Kbytes	1 Kbyte × 4	6 Kbytes	PLQP0080KB-A	N Version
R5F2L387CNFA	48 Kbytes	1 Kbyte × 4	6 Kbytes	PLQP0080JA-A	
R5F2L388CNFP	64 Kbytes	1 Kbyte × 4	8 Kbytes	PLQP0080KB-A	
R5F2L388CNFA	64 Kbytes	1 Kbyte × 4	8 Kbytes	PLQP0080JA-A	
R5F2L38ACNFP	96 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0080KB-A	
R5F2L38ACNFA	96 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0080JA-A	
R5F2L38CCNFP	128 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0080KB-A	
R5F2L38CCNFA	128 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0080JA-A	
R5F2L387CDFP	48 Kbytes	1 Kbyte × 4	6 Kbytes	PLQP0080KB-A	D Version
R5F2L387CDFA	48 Kbytes	1 Kbyte × 4	6 Kbytes	PLQP0080JA-A	
R5F2L388CDFP	64 Kbytes	1 Kbyte × 4	8 Kbytes	PLQP0080KB-A	
R5F2L388CDFA	64 Kbytes	1 Kbyte × 4	8 Kbytes	PLQP0080JA-A	
R5F2L38ACDFP	96 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0080KB-A	
R5F2L38ACDFA	96 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0080JA-A	
R5F2L38CCDFP	128 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0080KB-A	
R5F2L38CCDFA	128 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0080JA-A	

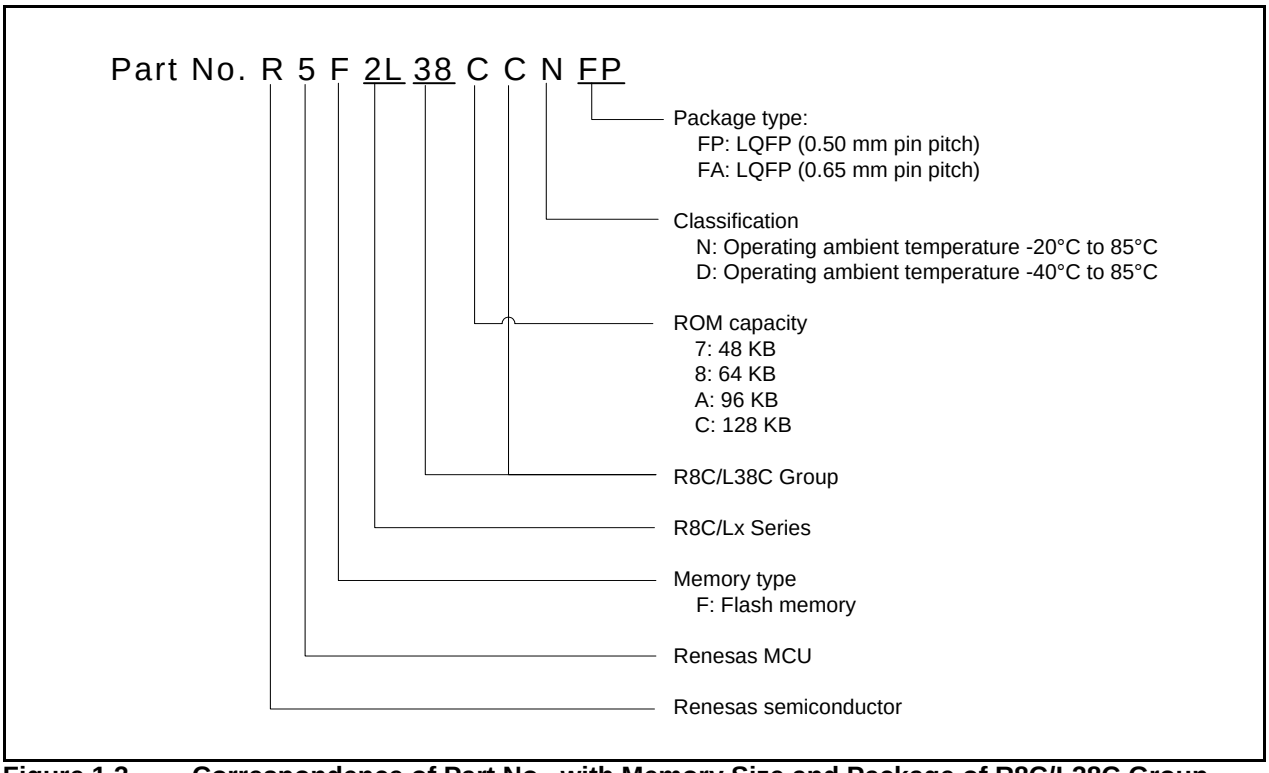


Figure 1.3 Correspondence of Part No., with Memory Size and Package of R8C/L38C Group

1.3 Block Diagrams

Figure 1.5 shows a Block Diagram of R8C/L35C Group. Figure 1.6 shows a Block Diagram of R8C/L36C Group. Figure 1.7 shows a Block Diagram of R8C/L38C Group. Figure 1.8 shows a Block Diagram of R8C/L3AC Group.

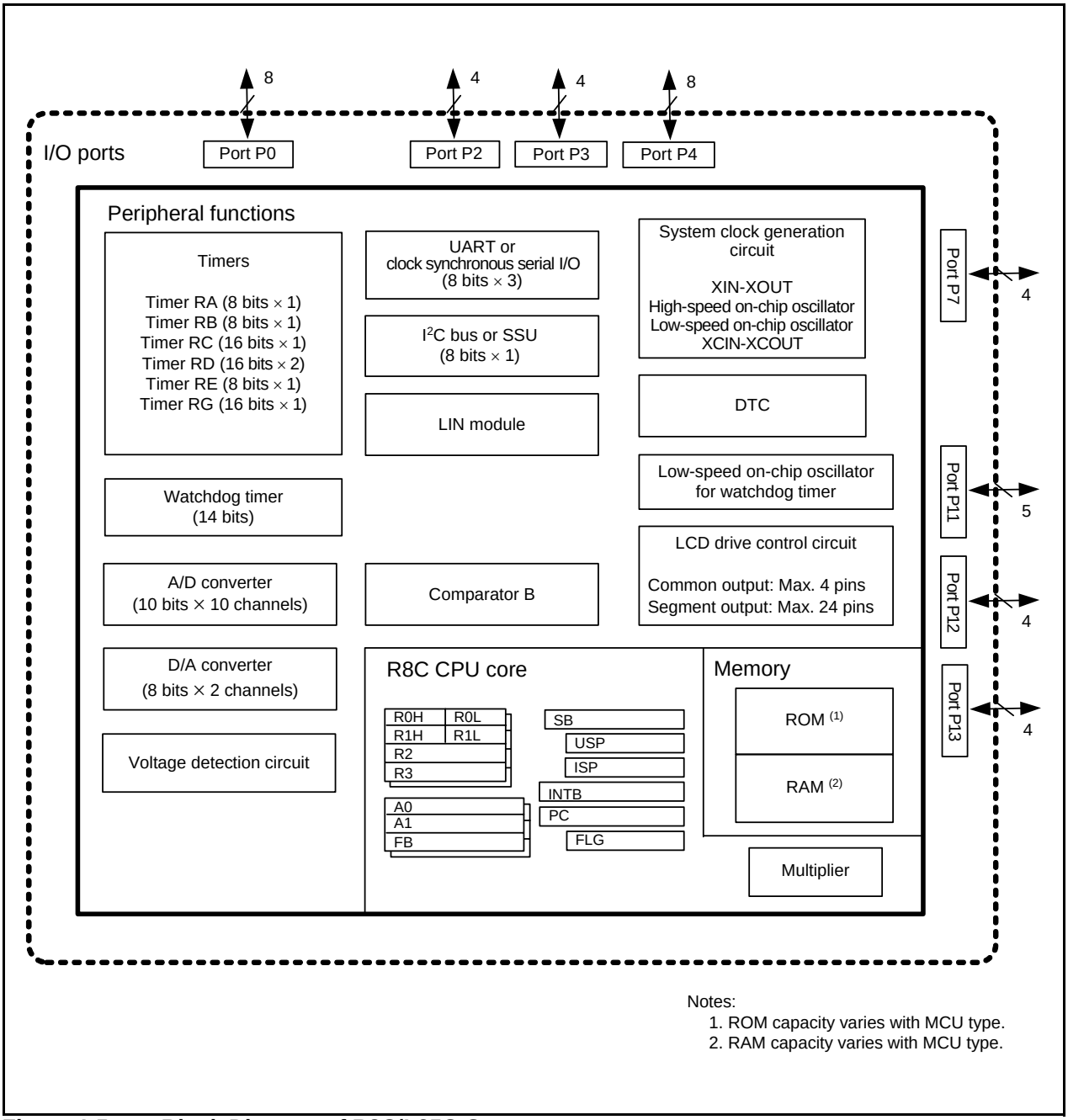
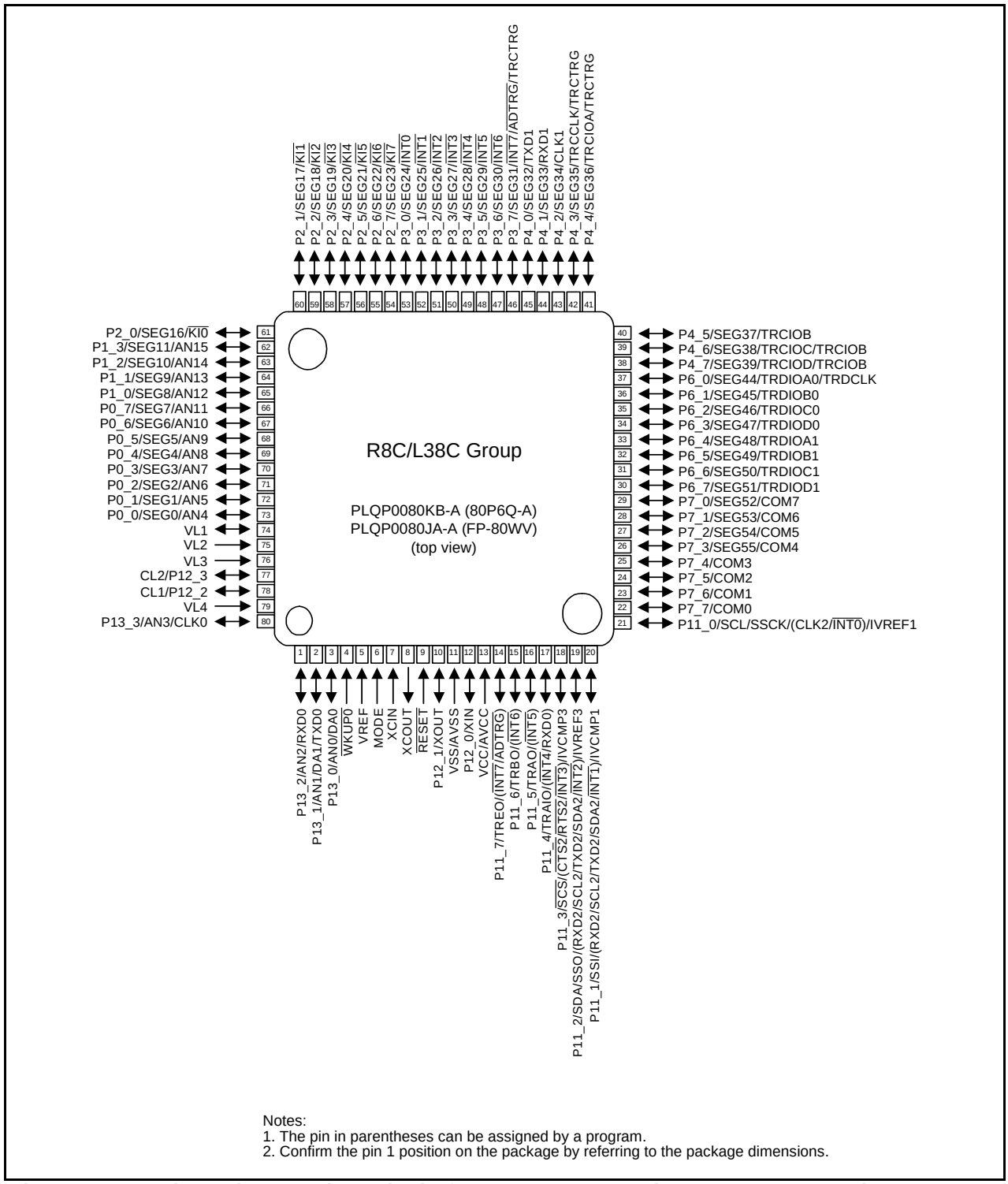


Figure 1.5 Block Diagram of R8C/L35C Group



Notes:
1. The pin in parentheses can be assigned by a program.
2. Confirm the pin 1 position on the package by referring to the package dimensions.

Figure 1.11 Pin Assignment (Top View) of PLQP0080KB-A and PLQP0080JA-A Packages

Table 1.13 Pin Name Information by Pin Number (3)

Pin Number				Control Pin	Port	I/O Pin Functions for Peripheral Modules						
L3AC (Note 2)	L38C	L36C	L35C			Interrupt	Timer	Serial Interface	SSU	I^2C bus	A/D Converter, D/A Converter, Comparator B	LCD drive control circuit
85 [87]	68	49	40		P0_5						AN9	SEG5
86 [88]	69	50	41		P0_4						AN8	SEG4
87 [89]	70	51	42		P0_3						AN7	SEG3
88 [90]	71	52	43		P0_2						AN6	SEG2
89 [91]	72	53	44		P0_1						AN5	SEG1
90 [92]	73	54	45		P0_0						AN4	SEG0
91 [93]	74	55	46									VL1
92 [94]	75	56	47									VL2
93 [95]	76	57										VL3
94 [96]	77	58	48		P12_3							CL2
95 [97]	78	59	49		P12_2							CL1
96 [98]	79	60	50									VL4
97 [99]					P13_7		TRGCLKB				AN19	
98 [100]					P13_6		TRGIOB				AN18	
99 [1]					P13_5		TRGCLKA				AN17	
100 [2]					P13_4		TRGIOA				AN16	

Notes:
1. The pin in parentheses can be assigned by a program.
2. The number in brackets indicates the pin number for the 100P6F package.

2.1 Data Registers (R0, R1, R2, and R3)

R0 is a 16-bit register for transfer, arithmetic, and logic operations. The same applies to R1 to R3. R0 can be split into high-order bits (R0H) and low-order bits (R0L) to be used separately as 8-bit data registers. R1H and R1L are analogous to R0H and R0L. R2 can be combined with R0 and used as a 32-bit data register (R2R0). R3R1 is analogous to R2R0.

2.2 Address Registers (A0 and A1)

A0 is a 16-bit register for address register indirect addressing and address register relative addressing. It is also used for transfer, arithmetic, and logic operations. A1 is analogous to A0. A1 can be combined with A0 and as a 32-bit address register (A1A0).

2.3 Frame Base Register (FB)

FB is a 16-bit register for FB relative addressing.

2.4 Interrupt Table Register (INTB)

INTB is a 20-bit register that indicates the starting address of an interrupt vector table.

2.5 Program Counter (PC)

PC is 20 bits wide and indicates the address of the next instruction to be executed.

2.6 User Stack Pointer (USP) and Interrupt Stack Pointer (ISP)

The stack pointers (SP), USP and ISP, are each 16 bits wide. The U flag of FLG is used to switch between USP and ISP.

2.7 Static Base Register (SB)

SB is a 16-bit register for SB relative addressing.

2.8 Flag Register (FLG)

FLG is an 11-bit register indicating the CPU state.

2.8.1 Carry Flag (C)

The C flag retains carry, borrow, or shift-out bits that have been generated by the arithmetic and logic unit.

2.8.2 Debug Flag (D)

The D flag is for debugging only. Set it to 0.

2.8.3 Zero Flag (Z)

The Z flag is set to 1 when an arithmetic operation results in 0; otherwise to 0.

2.8.4 Sign Flag (S)

The S flag is set to 1 when an arithmetic operation results in a negative value; otherwise to 0.

2.8.5 Register Bank Select Flag (B)

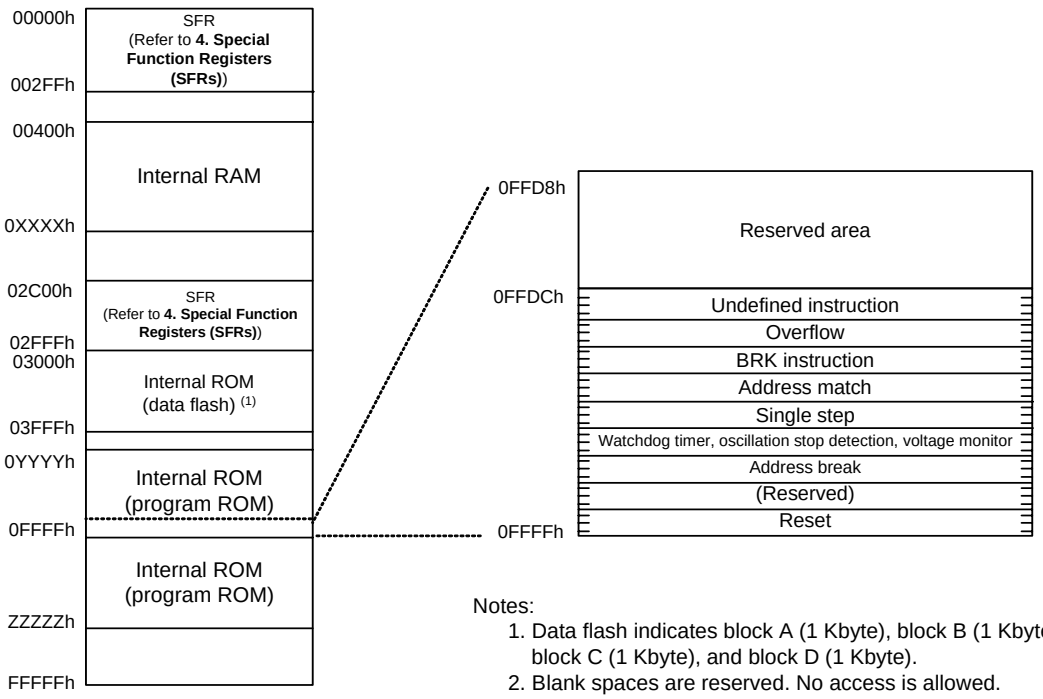
Register bank 0 is selected when the B flag is 0. Register bank 1 is selected when this flag is set to 1.

2.8.6 Overflow Flag (O)

The O flag is set to 1 when an operation results in an overflow; otherwise to 0.

3. Memory

Figure 3.1 is a Memory Map of each group. Each group has a 1-Mbyte address space from addresses 00000h to FFFFFh. For example, a 48-Kbyte internal ROM area is allocated addresses 04000h to 0FFFFh.
The fixed interrupt vector table is allocated addresses 0FFDCh to 0FFFFh. The starting address of each interrupt routine is stored here.
The internal ROM (data flash) is allocated addresses 03000h to 03FFFh.
The internal RAM is allocated higher addresses, beginning with address 00400h. For example, a 6-Kbyte internal RAM area is allocated addresses 00400h to 01BFFh. The internal RAM is used not only for data storage but also as a stack area when a subroutine is called or when an interrupt request is acknowledged.
Special function registers (SFRs) are allocated addresses 00000h to 002FFh and 02C00h to 02FFFh. Peripheral function control registers are allocated here. All unallocated spaces within the SFRs are reserved and cannot be accessed by users.



Notes:
1. Data flash indicates block A (1 Kbyte), block B (1 Kbyte), block C (1 Kbyte), and block D (1 Kbyte).
2. Blank spaces are reserved. No access is allowed.

Part Number	Internal ROM			Internal RAM	
	Capacity	Address 0YYYYh	Address ZZZZZh	Capacity	Address 0XXXXh
R5F2L357C***, R5F2L367C***, R5F2L387C***, R5F2L3A7C***	48 Kbytes	04000h	–	6 Kbytes	01BFFh
R5F2L358C***, R5F2L368C***, R5F2L388C***, R5F2L3A8C***	64 Kbytes	04000h	13FFFh	8 Kbytes	023FFh
R5F2L35AC***, R5F2L36AC***, R5F2L38AC***, R5F2L3AAC***	96 Kbytes	04000h	1BFFFh	10 Kbytes	02BFFh
R5F2L35CC***, R5F2L36CC***, R5F2L38CC***, R5F2L3ACC***	128 Kbytes	04000h	23FFFh	10 Kbytes	02BFFh

Figure 3.1 Memory Map

Table 4.6 SFR Information (6) (1)

Address	Register	Symbol	After Reset
0140h	Timer RD Control Register 0	TRDCR0	00h
0141h	Timer RD I/O Control Register A0	TRDIORA0	10001000b
0142h	Timer RD I/O Control Register C0	TRDIORC0	10001000b
0143h	Timer RD Status Register 0	TRDSR0	11100000b
0144h	Timer RD Interrupt Enable Register 0	TRDIER0	11100000b
0145h	Timer RD PWM Mode Output Level Control Register 0	TRDPOCR0	11111000b
0146h	Timer RD Counter 0	TRD0	00h
0147h			00h
0148h	Timer RD General Register A0	TRDGRA0	FFh
0149h			FFh
014Ah	Timer RD General Register B0	TRDGRB0	FFh
014Bh			FFh
014Ch	Timer RD General Register C0	TRDGRC0	FFh
014Dh			FFh
014Eh	Timer RD General Register D0	TRDGRD0	FFh
014Fh			FFh
0150h	Timer RD Control Register 1	TRDCR1	00h
0151h	Timer RD I/O Control Register A1	TRDIORA1	10001000b
0152h	Timer RD I/O Control Register C1	TRDIORC1	10001000b
0153h	Timer RD Status Register 1	TRDSR1	11000000b
0154h	Timer RD Interrupt Enable Register 1	TRDIER1	11100000b
0155h	Timer RD PWM Mode Output Level Control Register 1	TRDPOCR1	11111000b
0156h	Timer RD Counter 1	TRD1	00h
0157h			00h
0158h	Timer RD General Register A1	TRDGRA1	FFh
0159h			FFh
015Ah	Timer RD General Register B1	TRDGRB1	FFh
015Bh			FFh
015Ch	Timer RD General Register C1	TRDGRC1	FFh
015Dh			FFh
015Eh	Timer RD General Register D1	TRDGRD1	FFh
015Fh			FFh
0160h	UART1 Transmit/Receive Mode Register	U1MR	00h
0161h	UART1 Bit Rate Register	U1BRG	XXh
0162h	UART1 Transmit Buffer Register	U1TB	XXh
0163h			XXh
0164h	UART1 Transmit/Receive Control Register 0	U1C0	00001000b
0165h	UART1 Transmit/Receive Control Register 1	U1C1	00000010b
0166h	UART1 Receive Buffer Register	U1RB	XXh
0167h			XXh
0168h			
0169h			
016Ah			
016Bh			
016Ch			
016Dh			
016Eh			
016Fh			
0170h	Timer RG Mode Register	TRGMR	01000000b
0171h	Timer RG Count Control Register	TRGCNTC	00h
0172h	Timer RG Control Register	TRGCR	10000000b
0173h	Timer RG Interrupt Enable Register	TRGIER	11110000b
0174h	Timer RG Status Register	TRGSR	11100000b
0175h	Timer RG I/O Control Register	TRGIOR	00h
0176h	Timer RG Counter	TRG	00h
0177h			00h
0178h	Timer RG General Register A	TRGGRA	FFh
0179h			FFh
017Ah	Timer RG General Register B	TRGGRB	FFh
017Bh			FFh
017Ch	Timer RG General Register C	TRGGRC	FFh
017Dh			FFh
017Eh	Timer RG General Register D	TRGGRD	FFh
017Fh			FFh

X: Undefined

Note:

1. Blank spaces are reserved. No access is allowed.

Table 4.8 SFR Information (8) (1)

Address	Register	Symbol	After Reset
01C0h	Address Match Interrupt Register 0	RMAD0	XXh
01C1h			XXh
01C2h			0000XXXXb
01C3h	Address Match Interrupt Enable Register 0	AIER0	00h
01C4h	Address Match Interrupt Register 1	RMAD1	XXh
01C5h			XXh
01C6h			0000XXXXb
01C7h	Address Match Interrupt Enable Register 1	AIER1	00h
01C8h			
01C9h			
01CAh			
01CBh			
01CCh			
01CDh			
01CEh			
01CFh			
01D0h			
01D1h			
01D2h			
01D3h			
01D4h			
01D5h			
01D6h			
01D7h			
01D8h			
01D9h			
01DAh			
01DBh			
01DCh			
01DDh			
01DEh			
01DFh			
01E0h	Port P0 Pull-Up Control Register	P0PUR	00h
01E1h	Port P1 Pull-Up Control Register	P1PUR	00h
01E2h	Port P2 Pull-Up Control Register	P2PUR	00h
01E3h	Port P3 Pull-Up Control Register	P3PUR	00h
01E4h	Port P4 Pull-Up Control Register	P4PUR	00h
01E5h	Port P5 Pull-Up Control Register	P5PUR	00h
01E6h	Port P6 Pull-Up Control Register	P6PUR	00h
01E7h	Port P7 Pull-Up Control Register	P7PUR	00h
01E8h			
01E9h			
01EAh	Port 10 Pull-Up Control Register	P10PUR	00h
01EBh	Port 11 Pull-Up Control Register	P11PUR	00h
01ECh	Port 12 Pull-Up Control Register	P12PUR	00h
01EDh	Port 13 Pull-Up Control Register	P13PUR	00h
01EEh			
01EFh			
01F0h	Port P10 Drive Capacity Control Register	P10DRR	00h
01F1h	Port P11 Drive Capacity Control Register	P11DRR	00h
01F2h			
01F3h			
01F4h			
01F5h	Input Threshold Control Register 0	VLT0	00h
01F6h	Input Threshold Control Register 1	VLT1	00h
01F7h	Input Threshold Control Register 2	VLT2	00h
01F8h	Comparator B Control Register 0	INTCMP	00h
01F9h			
01FAh	External Input Enable Register 0	INTEN	00h
01FBh	External Input Enable Register 1	INTEN1	00h
01FCh	INT Input Filter Select Register 0	INTF	00h
01FDh	INT Input Filter Select Register 1	INTF1	00h
01FEh	Key Input Enable Register 0	KIEN	00h
01FFh	Key Input Enable Register 1	KIEN1	00h

X: Undefined

Note:

1. Blank spaces are reserved. No access is allowed.

Table 4.16 SFR Information (16) (1)

Address	Register	Symbol	After Reset
2CF0h	DTC Control Data 22	DTCD22	XXh
2CF1h			XXh
2CF2h			XXh
2CF3h			XXh
2CF4h			XXh
2CF5h			XXh
2CF6h			XXh
2CF7h			XXh
2CF8h	DTC Control Data 23	DTCD23	XXh
2CF9h			XXh
2CFAh			XXh
2CFBh			XXh
2CFCh			XXh
2CFDh			XXh
2CFEh			XXh
2CFFh			XXh
2D00h			
:			
2FFFh			

X: Undefined
Note:
1. Blank spaces are reserved. No access is allowed.

Table 4.17 ID Code Areas and Option Function Select Area

Address	Area Name	Symbol	After Reset
:			
FFDBh	Option Function Select Register 2	OFS2	(Note 1)
:			
FFDFh	ID1		(Note 2)
:			
FFE3h	ID2		(Note 2)
:			
FFEBh	ID3		(Note 2)
:			
FFEFh	ID4		(Note 2)
:			
FFF3h	ID5		(Note 2)
:			
FFF7h	ID6		(Note 2)
:			
FFFBh	ID7		(Note 2)
:			
FFFFh	Option Function Select Register	OFS	(Note 1)

Notes:
1. The option function select area is allocated in the flash memory, not in the SFRs. Set appropriate values as ROM data by a program.
   Do not write additions to the option function select area. If the block including the option function select area is erased, the option function select area is set to FFh.
   When blank products are shipped, the option function select area is set to FFh. It is set to the written value after written by the user.
   When factory-programming products are shipped, the value of the option function select area is the value programmed by the user.
2. The ID code areas are allocated in the flash memory, not in the SFRs. Set appropriate values as ROM data by a program.
   Do not write additions to the ID code areas. If the block including the ID code areas is erased, the ID code areas are set to FFh.
   When blank products are shipped, the ID code areas are set to FFh. They are set to the written value after written by the user.
   When factory-programming products are shipped, the value of the ID code areas is the value programmed by the user.

Table 5.6 Flash Memory (Program ROM) Characteristics
(V_{CC} = 2.7 to 5.5 V and T_{opr} = 0 to 60°C, unless otherwise specified.)

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
—	Program/erase endurance (1)		1,000 (2)	—	—	times
—	Byte program time		—	80	500	µs
—	Block erase time		—	0.3	—	s
$t_{d(SR-SUS)}$	Time delay from suspend request until suspend		—	—	5 + CPU clock × 3 cycles	ms
—	Interval from erase start/restart until following suspend request		0	—	—	ms
—	Time from suspend until erase restart		—	—	30+CPU clock × 1 cycle	µs
$t_{d(CMDRST-READY)}$	Time from when command is forcibly terminated until reading is enabled		—	—	30+CPU clock × 1 cycle	µs
—	Program, erase voltage		2.7	—	5.5	V
—	Read voltage		1.8	—	5.5	V
—	Program, erase temperature		0	—	60	°C
—	Data hold time (6)	Ambient temperature = 55°C	20	—	—	year

Notes:
1. Definition of programming/erasure endurance
   The programming and erasure endurance is defined on a per-block basis.
   If the programming and erasure endurance is n (n = 1,000), each block can be erased n times. For example, if 1,024 1-byte writes are performed to different addresses in block A, a 1 Kbyte block, and then the block is erased, the programming/erasure endurance still stands at one.
   However, the same address must not be programmed more than once per erase operation (overwriting prohibited).
2. Endurance to guarantee all electrical characteristics after program and erase. (1 to Min. value can be guaranteed).
3. In a system that executes multiple programming operations, the actual erasure count can be reduced by writing to sequential addresses in turn so that as much of the block as possible is used up before performing an erase operation. For example, when programming groups of 16 bytes, the effective number of rewrites can be minimized by programming up to 128 groups before erasing them all in one operation. It is also advisable to retain data on the erasure endurance of each block and limit the number of erase operations to a certain number.
4. If an error occurs during block erase, attempt to execute the clear status register command, then execute the block erase command at least three times until the erase error does not occur.
5. Customers desiring program/erase failure rate information should contact their Renesas technical support representative.
6. The data hold time includes time that the power supply is off or the clock is not supplied.

Table 5.10 Voltage Detection 2 Circuit Characteristics
(V_{CC} = 1.8 to 5.5 V and T_{opr} = –20 to 85°C (N version) / –40 to 85°C (D version), unless otherwise specified.)

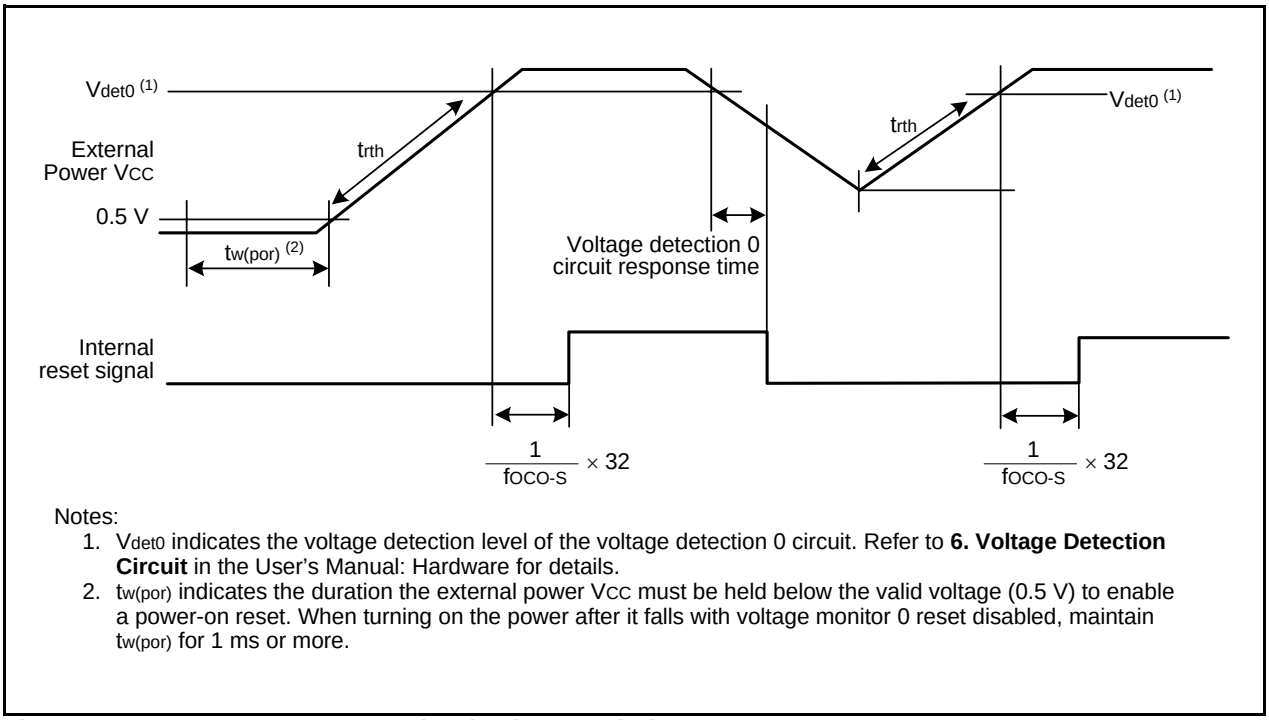
Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
V_{det2}	Voltage detection level Vdet2_0	At the falling of V_{CC}	3.70	4.00	4.30	V
—	Hysteresis width at the rising of Vcc in voltage detection 2 circuit		—	0.10	—	V
—	Voltage detection 2 circuit response time (1)	At the falling of Vcc from 5 V to (Vdet2_0 – 0.1) V	—	20	150	µs
—	Voltage detection circuit self power consumption	VCA27 = 1, V_{CC} = 5.0 V	—	1.7	—	µA
$t_{d(E-A)}$	Waiting time until voltage detection circuit operation starts (2)		—	—	100	µs

Notes:
1. Time until the voltage monitor 2 interrupt request is generated after the voltage passes V_{det2}.
2. Necessary time until the voltage detection circuit operates after setting to 1 again after setting the VCA27 bit in the VCA2 register to 0.

Table 5.11 Power-on Reset Circuit Characteristics (1)
(T_{opr} = –20 to 85°C (N version) / –40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
t_{rth}	External power V_{CC} rise gradient		0	—	50000	mV/msec

Note:
1. To use the power-on reset function, enable voltage monitor 0 reset by setting the LVDAS bit in the OFS register to 0.



Notes:
1. V_{det0} indicates the voltage detection level of the voltage detection 0 circuit. Refer to **6. Voltage Detection Circuit** in the User's Manual: Hardware for details.
2. $t_{w(por)}$ indicates the duration the external power V_{CC} must be held below the valid voltage (0.5 V) to enable a power-on reset. When turning on the power after it falls with voltage monitor 0 reset disabled, maintain $t_{w(por)}$ for 1 ms or more.

Figure 5.3 Power-on Reset Circuit Characteristics

Table 5.21 DC Characteristics (5) [1.8 V ≤ Vcc < 2.7 V]
(Topr = –20 to 85°C (N version) / –40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter		Condition	Standard			Unit
				Min.	Typ.	Max.	
V_{OH}	Output “H” voltage	Port P10, P11 (1)	I_{OH} = –2 mA	V_{CC} – 0.5	—	V_{CC}	V
		Other pins	I_{OH} = –1 mA	V_{CC} – 0.5	—	V_{CC}	V
		XOUT	I_{OH} = –200 μA	1.0	—	—	V
V_{OL}	Output “L” voltage	Port P10, P11 (1)	I_{OL} = 2 mA	—	—	0.5	V
		Other pins	I_{OL} = 1 mA	—	—	0.5	V
		XOUT	I_{OL} = 200 μA	—	—	0.5	V
V_{T+}-V_{T-}	Hysteresis	$\overline{INT0}$, $\overline{INT1}$, $\overline{INT2}$, $\overline{INT3}$, $\overline{INT4}$, INT5, $\overline{INT6}$, INT7, $\overline{KI0}$, $\overline{KI1}$, $\overline{KI2}$, $\overline{KI3}$, $\overline{KI4}$, $\overline{KI5}$, $\overline{KI6}$, $\overline{KI7}$, TRAIO, TRCIOA, TRCIOB, TRCIOC, TRCIOD, TRDIOA0, TRDIOB0, TRDIOC0, TRDIOD0, TRDIOA1, TRDIOB1, TRDIOC1, TRDIOD1, TRCTRG, TRCCLK, TRGCLKA, TRGCLKB, $\overline{TRGIOA}$, TRGIOB, $\overline{ADTRG}$, RXD0, RXD1, RXD2, CLK0, CLK1, CLK2, SSI, SCL, SDA, SSO		0.05	0.4	—	V
		$\overline{RESET}$, $\overline{WKUP0}$		0.1	0.8	—	V
I_{IH}	Input “H” current		VI = 1.8 V, V_{CC} = 1.8 V	—	—	4.0	μA
I_{IL}	Input “L” current		VI = 0 V, V_{CC} = 1.8 V	—	—	–4.0	μA
R_{PULLUP}	Pull-up resistance		VI = 0 V, V_{CC} = 1.8 V	60	160	420	kΩ
R_{fXIN}	Feedback resistance	XIN		—	0.3	—	MΩ
R_{fXCIN}	Feedback resistance	XCIN		—	14	—	MΩ
V_{RAM}	RAM hold voltage		During stop mode	1.8	—	—	V

Note:
1. This applies when the drive capacity of the output transistor is set to High by registers P10DRR and P11DRR. When the drive capacity is set to Low, the value of any other pin applies.

5.5 AC Characteristics

Table 5.23 Timing Requirements of Synchronous Serial Communication Unit (SSU) (V_{CC} = 1.8 to 5.5 V, V_{SS} = 0 V, and T_{opr} = −20 to 85°C (N version) / −40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter		Conditions	Standard			Unit
				Min.	Typ.	Max.	
t_{SUCYC}	SSCK clock cycle time			4	—	—	t_{CYC} (1)
t_{HI}	SSCK clock “H” width			0.4	—	0.6	t_{SUCYC}
t_{LO}	SSCK clock “L” width			0.4	—	0.6	t_{SUCYC}
t_{RISE}	SSCK clock rising time	Master		—	—	1	t_{CYC} (1)
		Slave		—	—	1	µs
t_{FALL}	SSCK clock falling time	Master		—	—	1	t_{CYC} (1)
		Slave		—	—	1	µs
t_{SU}	SSO, SSI data input setup time			100	—	—	ns
t_H	SSO, SSI data input hold time			1	—	—	t_{CYC} (1)
t_{LEAD}	$\overline{SCS}$ setup time	Slave		1t_{CYC} + 50	—	—	ns
t_{LAG}	$\overline{SCS}$ hold time	Slave		1t_{CYC} + 50	—	—	ns
t_{OD}	SSO, SSI data output delay time			—	—	1	t_{CYC} (1)
t_{SA}	SSI slave access time		2.7 V ≤ V_{CC} ≤ 5.5 V	—	—	1.5t_{CYC} + 100	ns
			1.8 V ≤ V_{CC} < 2.7 V	—	—	1.5t_{CYC} + 200	ns
t_{OR}	SSI slave out open time		2.7 V ≤ V_{CC} ≤ 5.5 V	—	—	1.5t_{CYC} + 100	ns
			1.8 V ≤ V_{CC} < 2.7 V	—	—	1.5t_{CYC} + 200	ns

Note:
1. 1t_{CYC} = 1/f1(s)

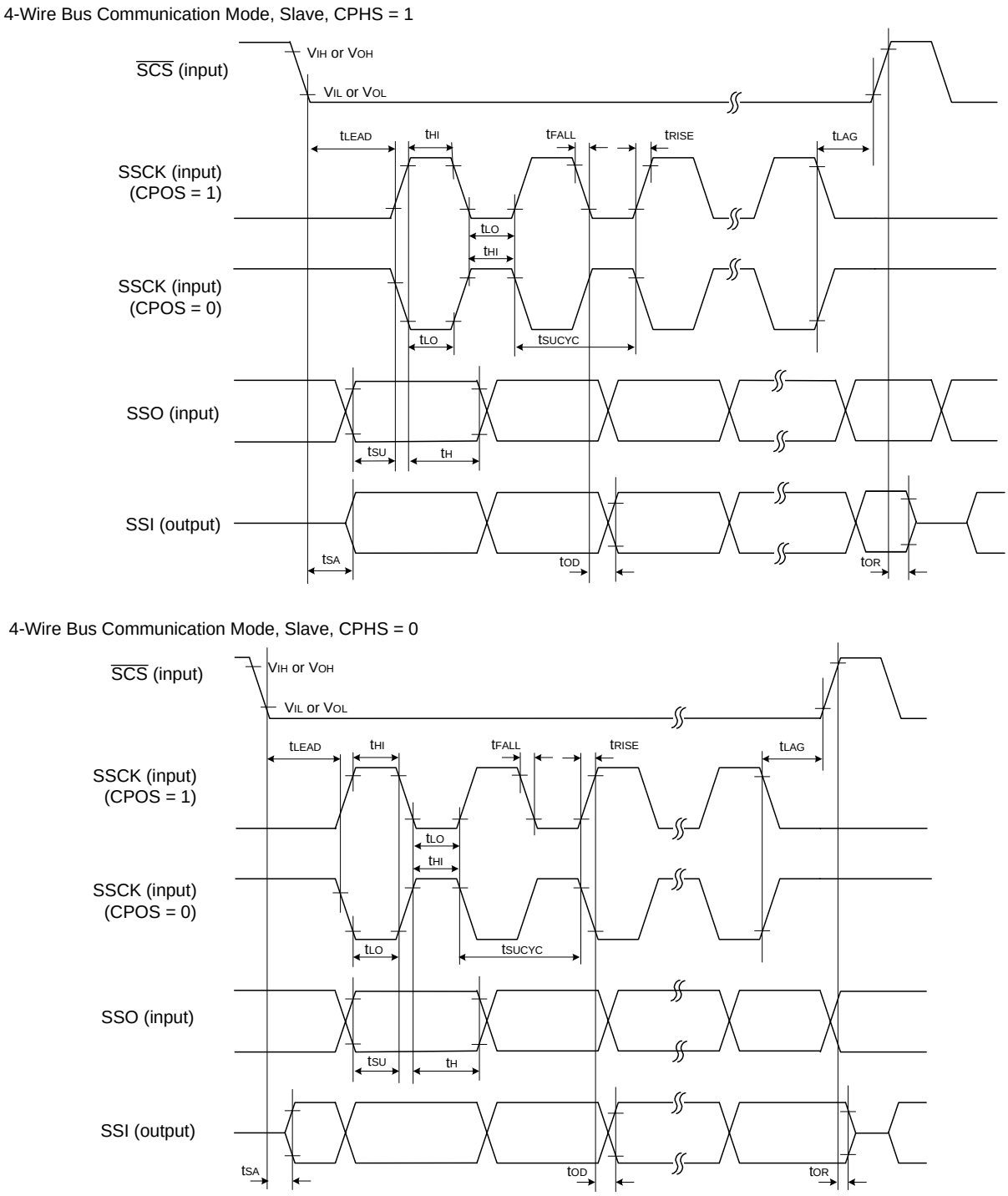


Figure 5.5 I/O Timing of Synchronous Serial Communication Unit (SSU) (Slave)

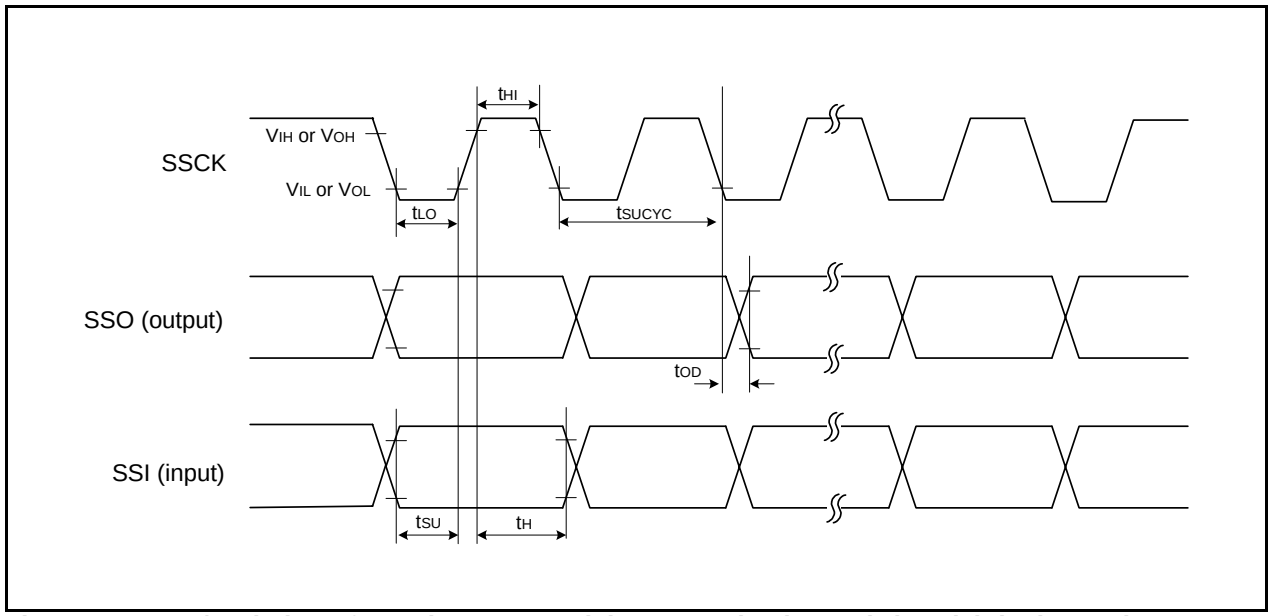
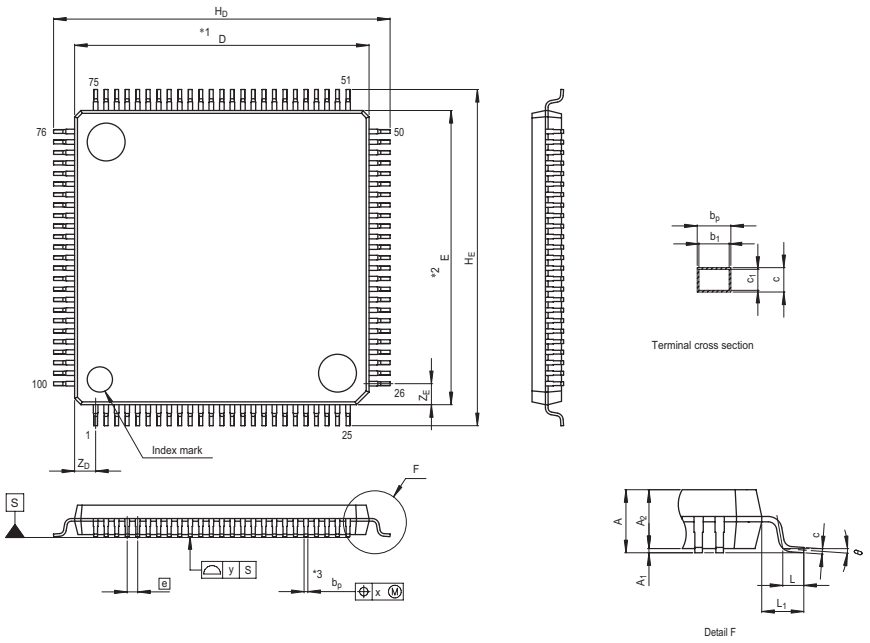


Figure 5.6 I/O Timing of Synchronous Serial Communication Unit (SSU) (Clock Synchronous Communication Mode)

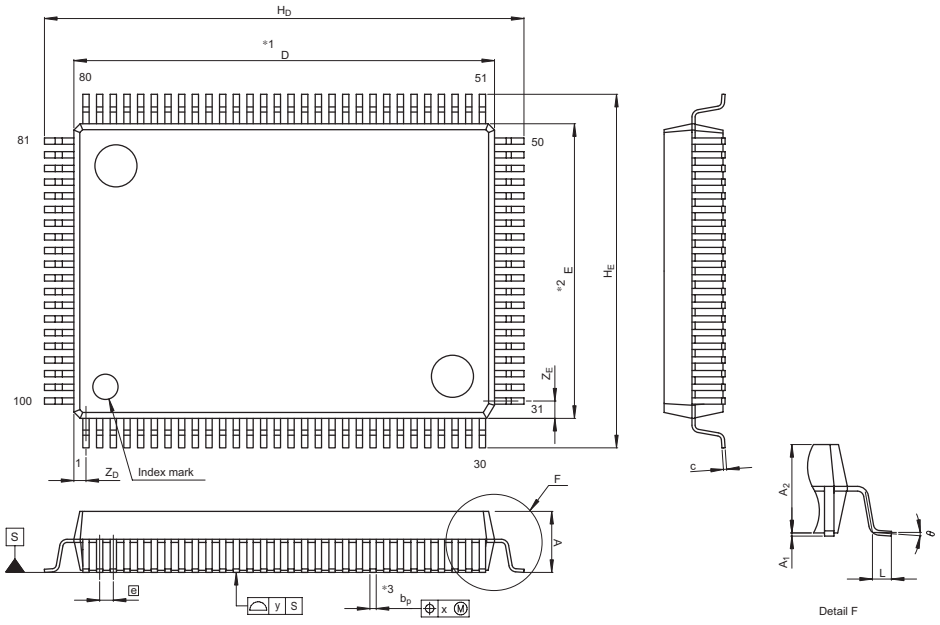
JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-LQFP100-14x14-0.50	PLQP0100KB-A	100P6Q-A / FP-100U / FP-100UV	0.6g



NOTE)
1. DIMENSIONS "*1" AND "*2" DO NOT INCLUDE MOLD FLASH.
2. DIMENSION "*3" DOES NOT INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	13.9	14.0	14.1
E	13.9	14.0	14.1
A_2	—	1.4	—
H_D	15.8	16.0	16.2
H_E	15.8	16.0	16.2
A	—	—	1.7
A_1	0.05	0.1	0.15
b_p	0.15	0.20	0.25
b_1	—	0.18	—
c	0.09	0.145	0.20
c_1	—	0.125	—
θ	0°	—	8°
e	—	0.5	—
x	—	—	0.08
y	—	—	0.08
Z_D	—	1.0	—
Z_E	—	1.0	—
L	0.35	0.5	0.65
L_1	—	1.0	—

JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-QFP100-14x20-0.65	PRQP0100JD-B	100P6F-A	1.8g



NOTE)
1. DIMENSIONS "*1" AND "*2" DO NOT INCLUDE MOLD FLASH.
2. DIMENSION "*3" DOES NOT INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	19.8	20.0	20.2
E	13.8	14.0	14.2
A_2	—	2.8	—
H_D	22.5	22.8	23.1
H_E	16.5	16.8	17.1
A	—	—	3.05
A_1	0	0.1	0.2
b_p	0.25	0.3	0.4
c	0.13	0.15	0.2
θ	0°	—	10°
e	—	0.65	—
x	—	—	0.13
y	—	—	0.10
Z_D	—	0.575	—
Z_E	—	0.825	—
L	0.4	0.6	0.8

General Precautions in the Handling of MPU/MCU Products

The following usage notes are applicable to all MPU/MCU products from Renesas. For detailed usage notes on the products covered by this manual, refer to the relevant sections of the manual. If the descriptions under General Precautions in the Handling of MPU/MCU Products and in the body of the manual differ from each other, the description in the body of the manual takes precedence.

1. Handling of Unused Pins

   Handle unused pins in accord with the directions given under Handling of Unused Pins in the manual.

   — The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible. Unused pins should be handled as described under Handling of Unused Pins in the manual.

2. Processing at Power-on

   The state of the product is undefined at the moment when power is supplied.

   — The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the moment when power is supplied.

   In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the moment when power is supplied until the reset process is completed.

   In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the moment when power is supplied until the power reaches the level at which resetting has been specified.

3. Prohibition of Access to Reserved Addresses

   Access to reserved addresses is prohibited.

   — The reserved addresses are provided for the possible future expansion of functions. Do not access these addresses; the correct operation of LSI is not guaranteed if they are accessed.

4. Clock Signals

   After applying a reset, only release the reset line after the operating clock signal has become stable. When switching the clock signal during program execution, wait until the target clock signal has stabilized.

   — When the clock signal is generated with an external resonator (or from an external oscillator) during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Moreover, when switching to a clock signal produced with an external resonator (or by an external oscillator) while program execution is in progress, wait until the target clock signal is stable.

5. Differences between Products

   Before changing from one product to another, i.e. to one with a different part number, confirm that the change will not lead to problems.

   — The characteristics of MPU/MCU in the same group but having different part numbers may differ because of the differences in internal memory capacity and layout pattern. When changing to products of different part numbers, implement a system-evaluation test for each of the products.